



Final Product Change Notification

201510004F01

Issue Date: 10-Jun-2016

Effective Date: 05-Aug-2016

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Management Summary

Change to state of the art lithography tools and introduction of advanced die protection technology.

Please refer to APCN 201510004A from 30-Oct-2015.

Change Category

<input checked="" type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage

Change of AMR photolithography tool and implementation of additional wafer coating

Details of this Change

1. Photolithography tool will be changed from PE mask aligner tool towards PAS stepper tool.

This requires adaption of wafer layout and new mask sets.

Die design will not be changed.

Individual information about die coordinates in the die layout will be removed because of stepper technology.

Stepper lithography is the more advanced standard technology in wafer fab processing.

2. Additional wafer coat layer as surface protection

This requires an additional mask step.

Wafer coat protection is standard process in IC wafer fab manufacturing.

Why do we Implement this Change

1. Discontinuation of old photolithography technology.

Stepper lithography delivers improved accuracy.

2. Robustness improvement against potential surface damages and contamination.

Reduction of mechanical package stress on the die.

Identification of Affected Products

Identification by lot-ID and datecodes on labels on packages

Product Availability

Sample Information

Samples are available from 01-Feb-2016

Production

Planned first shipment 01-Sep-2016

Impact

no impact to the product's functionality anticipated.

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 10-Jul-2016.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Ingoert Gorlt
Position Customer Quality Manager
e-mail address ingoert.gorlt@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[| Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.